

## ABSTRACT OF THE DISCLOSURE

A stopper for chemical mechanical planarization comprising an organosilicon polymer, in particular a polycarbosilane, is provided. The stopper used for polishing  
5 wafers with a wiring pattern in the manufacture of semiconductor devices to protect interlayer dielectric films made of a material such as  $\text{SiO}_2$ , fluorine dope  $\text{SiO}_2$ , or organic or inorganic SOG (Spin-on glass) from damages during the chemical mechanical planarization process.

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